Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	426	((micromechanical or MEMS or microelectromechanical or microstructure$1 or (acceleration adj sensor) or accelerometer)) and (wafer near3 bond$3).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/21 14:09
L2	124	((micromechanical or MEMS or microelectromechanical or microstructure$1 or (acceleration adj sensor) or accelerometer)) and ((second adj wafer) with (bond$3 or attach$3)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/21 14:04
L3	451	l1 or l2	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/21 14:04
L4	75	((micromechanical or MEMS or microelectromechanical or microstructure$1 or (acceleration adj sensor) or accelerometer)) and christenson.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/21 14:09
S1	1791	216/2	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/10 10:26
S2	480	216/11	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 18:10
S3	544	216/17	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 18:10
S4	363	216/20	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 18:10
S5	908	216/24	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 18:10

S6	420	216/33	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 18:11
S7	122	216/36	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 18:11
S8	1457	438/22	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 18:11
S9	232	(438/24).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 18:11
S10	785	(438/48).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 18:11
S11	444	(438/50).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 18:12
S12	482	(438/52).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 18:12
S13	626	(438/53).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 18:12
S14	1516	(438/689).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 18:12
S15	3752	(438/694).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 18:12

S16	461	(438/696).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 18:12
S17	956	(438/700).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 18:12
S18	867	(438/702).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 18:20
S19	3303	(73/514.15-514.39).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 18:23
S20	1557	(257/417-419).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 18:21
S21	2901	(257/414-419).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 18:21
S22	2	(S19 or S20 or S21) and (second adj sealing adj layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/15 16:15
S23	4	(micromechanical) and (second adj sealing adj layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/10 11:05
S24	2	(micromechanical) and (sealing adj oxide)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 18:35
S25	358	((micromechanical or MEMS or microelectromechanical) and ((etch$3 or remov$3) and $2oxide$1 and silicon)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 18:38

S26	478	((micromechanical or MEMS or microelectromechanical) and ($2oxide$1 and silicon)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 18:38
S27	645	(micromechanical or MEMS or microelectromechanical) and ($2oxide$1 and silicon) and (TEOS or LTO)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 18:39
S28	416	((micromechanical or MEMS or microelectromechanical or (acceleration adj sensor) or accelerometer)).clm. and ($2oxide$1 and silicon) and comb	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/08 18:34
S29	2398	((micromechanical or MEMS or microelectromechanical or (acceleration adj sensor) or accelerometer)).clm. and ($2oxide$1 and silicon)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 18:41
S30	28	(S19 or S20 or S21) and (second adj oxide adj layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 18:43
S31	24	"0187765"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/07 12:59
S32	2837420	WO 01/87765 A2	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/07 13:02
S33	0	01/87765	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/07 13:00
S34	26	"87765"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/07 13:00
S35	0	WO0187765	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/07 13:03

S36	24	"0187765"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/07 13:04
S37	0	WO-0187765-$.did.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/07 13:04
S38	0	WO-0177009-$.did.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/07 13:04
S39	22	"0177009"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/07 13:05
S40	197	(micromechanical and component).ti.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/07 14:07
S41	11057	(micromechanical or mems or microelectro$11).ti.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/07 14:07
S42	4222	(micromechanical or mems or microelectromechanical).ti.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/07 14:11
S43	3834	(micromechanical or mems or microelectromechanical).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/07 14:08
S44	7870	(micromechanical or mems or microelectromechanical).ab.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/07 14:08
S45	2151	(S42 or S43 or S44) and etch$3 and layer and $2oxide and silicon	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/07 14:09

S46	2234	(S42 or S43 or S44) and etch$3 and $2oxide and silicon	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/07 14:10
S47	136	(S42 or S43 or S44) and etch$3 and $2oxide and silicon and bosch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/07 14:10
S48	423	(S42 or S43 or S44) and etch$3 and $2oxide and silicon and (accelerometer or (acceleration with sensor$1))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/07 14:11
S49	6	(micromechanical or mems or microelectromechanical) and $2oxide	JPO	OR	OFF	2005/06/07 14:12
S50	17	(micromechanical or mems or microelectromechanical) and seal$3	JPO	OR	OFF	2005/06/07 14:12
S51	81	((micromechanical or MEMS or microelectromechanical or (acceleration adj sensor) or accelerometer)).clm. and (comb with (teeth or tooth))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/08 18:34
S52	91	((micromechanical or MEMS or microelectromechanical or microstructure$1 or (acceleration adj sensor) or accelerometer)).clm. and (comb with (teeth or tooth))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/08 18:35
S53	2300	((micromechanical or MEMS or microelectromechanical or microstructure$1 or (acceleration adj sensor) or accelerometer)).ti. and (method or process).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/13 16:51
S54	18630	((micromechanical or MEMS or microelectromechanical or microstructure$1 or (acceleration adj sensor) or accelerometer)).ti.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/08 18:36
S55	1094	((micromechanical or MEMS or microelectromechanical or microstructure$1 or (acceleration adj sensor) or accelerometer)).ti. and substrate and layer and (etch$3 or remov$3 or trench).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/08 18:37

S56	744	((micromechanical or MEMS or microelectromechanical or microstructure$1 or (acceleration adj sensor) or accelerometer)).ti. and (substrate and layer and (etch$3 or remov$3 or trench)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/08 18:37
S57	158	((micromechanical or MEMS or microelectromechanical or microstructure$1 or (acceleration adj sensor) or accelerometer)).ti. and substrate and layer and (etch$3 or remov$3 or trench).clm. and comb	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/08 18:38
S58	276	((micromechanical or MEMS or microelectromechanical or microstructure$1 or (acceleration adj sensor) or accelerometer)).ti. and (substrate and layer and (etch$3 or remov$3 or trench) and ((release adj layer) or sacrificial)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/08 18:42
S59	43	((micromechanical or MEMS or microelectromechanical or microstructure$1 or (acceleration adj sensor) or accelerometer)).ti. and (substrate and layer and (etch$3 or remov$3 or trench) and ((release adj layer) or sacrificial))	EPO; JPO	OR	OFF	2005/06/08 18:39
S60	111	((micromechanical or MEMS or microelectromechanical or microstructure$1 or (acceleration adj sensor) or accelerometer)).ti. and (substrate and layer and (etch$3 or remov$3 or trench) and ((release adj layer) or sacrificial))	DERWENT	OR	OFF	2005/06/08 18:40
S61	44	((micromechanical or MEMS or microelectromechanical or microstructure$1 or (acceleration adj sensor) or accelerometer)).ti. and (sealing adj (oxide or layer))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/08 18:43
S62	66	((micromechanical or MEMS or microelectromechanical or microstructure$1 or (acceleration adj sensor) or accelerometer)).clm. and (sealing adj (oxide or layer))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/08 18:43
S63	26	((micromechanical or MEMS or microelectromechanical or microstructure$1 or (acceleration adj sensor) or accelerometer)).clm. and (sealing adj (oxide or layer)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/08 18:49

S64	16	("4882933" | "5006487" | "5181156" | "5241864" | "5258097" | "5262000" | "5429993" | "5510290" | "5559290" | "5587343" | "5604313" | "5611940" | "5784212" | "5830777" | "5834332" | "5861673").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/06/08 18:46
S65	7	("5130276" | "5164328" | "5258097" | "5324683" | "5326726" | "5616523" | "5656512").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/06/08 18:47
S66	27	((micromechanical or MEMS or microelectromechanical or micromachined or microstructure$1 or (acceleration adj sensor) or accelerometer)).clm. and (sealing adj (oxide or layer)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/09 16:06
S67	1180	((micromechanical or MEMS or microelectromechanical or microstructure$1 or (acceleration adj sensor) or accelerometer)) and bosch.as.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/08 18:49
S68	200	((micromechanical or MEMS or microelectromechanical or microstructure$1 or (acceleration adj sensor) or accelerometer)) and lutz.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/08 18:50
S69	2	("4665610").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/09 16:05
S70	1	1987-156559.NRAN.	DERWENT	OR	OFF	2005/06/09 16:05
S71	37	((micromechanical or MEMS or microelectromechanical or micromachined or microstructure$1 or (acceleration adj sensor) or accelerometer or transducer)).clm. and (sealing adj (oxide or layer)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/09 16:16
S72	906	((micromechanical or MEMS or microelectromechanical or micromachined or microstructure$1 or (acceleration adj sensor) or accelerometer or transducer)).clm. and (anchor$3).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/09 16:06

S73	188	((micromechanical or MEMS or microelectromechanical or micromachined or microstructure$1 or (acceleration adj sensor) or accelerometer or transducer)).clm. and (anchor$3 and layer and second).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/09 16:09
S74	1713	((micromechanical or MEMS or microelectromechanical or micromachined or microstructure$1 or (acceleration adj sensor) or accelerometer or transducer)).clm. and (second adj2 layer).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/15 16:15
S75	548	((micromechanical or MEMS or microelectromechanical or micromachined or microstructure$1 or (acceleration adj sensor) or accelerometer or transducer)).clm. and (sacrificial). clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/13 13:59
S76	137	((micromechanical or MEMS or microelectromechanical or micromachined or microstructure$1 or (acceleration adj sensor) or accelerometer or transducer)).clm. and (sacrificial and thickness).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/09 16:10
S77	58	((micromechanical or MEMS or microelectromechanical or micromachined or microstructure$1 or (acceleration adj sensor) or accelerometer or transducer)).clm. and (sacrificial and anchor$3).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/09 16:13
S78	538	((micromechanical or MEMS or microelectromechanical or micromachined or microstructure$1 or (acceleration adj sensor) or accelerometer or transducer)).clm. and (oxide and (cap$4 or seal$3)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/09 16:20
S79	13	((micromechanical or MEMS or microelectromechanical or micromachined or microstructure$1 or (acceleration adj sensor) or accelerometer or transducer)).clm. and (oxide and (fourth adj layer)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/10 10:45

S80	2	("4665610").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/10 10:26
S81	2	("4332000" | "4588472").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/06/10 10:27
S82	2961	((micromechanical or MEMS or microelectromechanical or micromachined or microstructure$1 or (acceleration adj sensor) or accelerometer or transducer)).clm. and (diaphragm).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/10 10:30
S83	279	((micromechanical or MEMS or microelectromechanical or micromachined or microstructure$1 or (acceleration adj sensor) or accelerometer or transducer)).clm. and ((multiple or second) adj2 diaphragm).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/10 10:30
S84	721	((micromechanical or MEMS or microelectromechanical or micromachined or microstructure$1 or (acceleration adj sensor) or accelerometer or transducer)).clm. and (encapsulat$3).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/10 10:46
S85	33	((micromechanical or MEMS or microelectromechanical or micromachined or microstructure$1 or (acceleration adj sensor) or accelerometer or transducer)).clm. and (encapsulat$3 and polysilicon).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/10 10:50
S86	643	((micromechanical or MEMS or microelectromechanical or micromachined or microstructure$1 or (acceleration adj sensor) or accelerometer or transducer)).clm. and (bosch and robert).as.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/10 10:52
S87	50	((micromechanical or MEMS or microelectromechanical or micromachined or microstructure$1 or (acceleration adj sensor) or accelerometer or transducer)).clm. and (bosch and robert).as. and diaphragm	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/10 10:53

S88	393	((micromechanical or MEMS or microelectromechanical or micromachined or microstructure$1 or (acceleration adj sensor) or accelerometer or transducer)).clm. and (bosch and robert).as. and second.clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/10 10:54
S89	42	((micromechanical or MEMS or microelectromechanical or micromachined or microstructure$1 or (acceleration adj sensor) or accelerometer or transducer)).clm. and (bosch and robert).as. and sealing	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/10 10:55
S90	155	((micromechanical or MEMS or microelectromechanical or micromachined or microstructure$1 or (acceleration adj sensor) or accelerometer or transducer)).clm. and ((conformal or (vapor adj deposition)) and oxide).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/10 10:55
S91	21	micromechanical and siemens and (christofer and hierold).in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/10 11:07
S92	15	"5760455"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/13 10:54
S93	2	"19537814"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/13 10:56
S94	3	(("5756901") or ("6030850")).PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/13 10:56
S95	9	((micromechanical or MEMS or microelectromechanical or micromachined or microstructure$1 or (acceleration adj sensor) or accelerometer or transducer)).clm. and (post$1 with taper$2).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/13 14:06

S96	172	((micromechanical or MEMS or microelectromechanical or micromachined or microstructure$1 or (acceleration adj sensor) or accelerometer or transducer)).clm. and ((hole$1 or opening$1) with taper$2).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/13 15:14
S97	412	((micromechanical or MEMS or microelectromechanical or micromachined or microstructure$1 or (acceleration adj sensor) or accelerometer or transducer)).clm. and ((hole$1 or opening$1 or trench$2) with width).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/13 15:17
S98	1365	((micromechanical or MEMS or microelectromechanical or micromachined or microstructure$1 or (acceleration adj sensor) or accelerometer or transducer)).clm. and ((hole$1 or opening$1 or trench$2) with width)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/13 15:17
S99	171	((micromechanical or MEMS or microelectromechanical or micromachined or microstructure$1 or (acceleration adj sensor) or accelerometer or transducer)).clm. and ((hole$1 or opening$1 or trench$2) with width) and $2oxide with deposit$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/13 15:18
S100	171	((micromechanical or MEMS or microelectromechanical or micromachined or microstructure$1 or (acceleration adj sensor) or accelerometer or transducer)).clm. and ((hole$1 or opening$1 or trench$2) with width) and ($2oxide with deposit$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/13 15:18
S101	5	((micromechanical or MEMS or microelectromechanical or microstructure$1 or (acceleration adj sensor) or accelerometer)).ti. and (comb or zipper$3 or electrostatic) and ((tooth or teeth) with width)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/13 16:53

S10 2	75	((micromechanical or MEMS or microelectromechanical or microstructure$1 or (acceleration adj sensor) or accelerometer)).ti. and (comb or zipper$3 or electrostatic) and ((tooth or teeth or trenches or holes or prongs or fingers) with width)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/13 17:00
S10 3	29	((micromechanical or MEMS or microelectromechanical or microstructure$1 or (acceleration adj sensor) or accelerometer)).ti. and (comb or zipper$3 or electrostatic) and ((tooth or teeth or trenches or holes or prongs or fingers) with width) and sacrificial	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/13 16:58
S10 4	369	((micromechanical or MEMS or microelectromechanical or microstructure$1 or (acceleration adj sensor) or accelerometer)) and (comb or zipper$3 or electrostatic) and ((tooth or teeth or trenches or holes or prongs or fingers) with width)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/13 17:01
S10 5	236	((micromechanical or MEMS or microelectromechanical or microstructure$1 or (acceleration adj sensor) or accelerometer)) and (comb or zipper$3) and ((tooth or teeth or trenches or holes or prongs or fingers) with width)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/13 17:01
S10 6	231	((micromechanical or MEMS or microelectromechanical or microstructure$1 or (acceleration adj sensor) or accelerometer)) and comb and ((tooth or teeth or trenches or holes or prongs or fingers) with width)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/13 17:46
S10 7	180007	cavitation bubbles	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/13 17:46
S10 8	1182	cavitation adj bubbles	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/13 17:46
S10 9	6	(cavitation adj bubbles) and (target adj bubble)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/13 17:47

S11 0	3312	(73/514.15-514.39).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/14 11:46
S11 1	1558	(257/417-419).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/14 11:46
S11 2	2910	(257/414-419).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/14 11:46
S11 3	45	(S110 or S111 or S112) and comb and ((tooth or teeth or trenches or holes or prongs or fingers) with width)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/14 11:47
S11 5	65	(S110 or S111 or S112) and comb and ((tooth or teeth or trenches or holes or prongs or fingers) with (distance or width))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/14 11:53
S11 6	89	(S110 or S111 or S112) and comb$5 and ((tooth or teeth or trenches or holes or prongs or fingers) with (distance or width))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/14 12:00
S11 7	21	(S110 or S111 or S112) and comb$5 and (helical)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/14 12:00
S11 8	422	(S110 or S111 or S112) and comb$5 and spring	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/14 12:00
S11 9	14	(S110 or S111 or S112) and comb$5 and spring and ((fold$1 or coil$1) with (distance or width))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/14 12:01
S12 0	320	((micromechanical or MEMS or microelectromechanical or microstructure$1 or (acceleration adj sensor) or accelerometer))and comb$5 and spring and ((fold$1 or coil$1) with (distance or width))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/14 12:23

S12 1	89	((micromechanical or MEMS or microelectromechanical or microstructure$1 or (acceleration adj sensor) or accelerometer))and (comb$5 or electrostatic).clm. and spring and ((fold$1 or coil$1) with (distance or width))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/14 12:26
S12 2	2240	((micromechanical or MEMS or microelectromechanical or microstructure$1 or (acceleration adj sensor) or accelerometer))and (comb$5 or electrostatic).clm. and (spring$1 or flexure$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/14 12:26
S12 3	657	((micromechanical or MEMS or microelectromechanical or microstructure$1 or (acceleration adj sensor) or accelerometer))and (comb$5 or electrostatic).clm. and (spring$1 or flexure$1).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/14 12:27
S12 4	206	((micromechanical or MEMS or microelectromechanical or microstructure$1 or (acceleration adj sensor) or accelerometer))and (comb$5 or electrostatic).clm. and (spring$1 or flexure$1).clm. and (distance or width).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/20 13:30
S12 7	66970	((micromechanical or MEMS or microelectromechanical or micromachined or microstructure$1 or (acceleration adj sensor) or accelerometer or transducer)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/15 17:18
S12 8	3312	(73/514.15-514.39).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/15 16:15
S12 9	1558	(257/417-419).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/15 16:15
S13 0	2910	(257/414-419).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/15 16:15
S13 1	6104	(S128 or S129 or S130)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/15 16:15

S13 2	1802	216/2	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/15 16:17
S13 3	485	216/11	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/15 16:17
S13 4	550	216/17	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/15 16:17
S13 5	367	216/20	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/15 16:17
S13 6	915	216/24	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/15 16:17
S13 7	422	216/33	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/15 16:17
S13 8	122	216/36	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/15 16:17
S13 9	1472	438/22	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/15 16:17
S14 0	233	(438/24).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/15 16:17
S14 1	793	(438/48).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/15 16:17

S14 2	446	(438/50).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/15 16:17
S14 3	486	(438/52).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/15 16:17
S14 4	627	(438/53).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/15 16:17
S14 5	1524	(438/689).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/15 16:17
S14 6	3757	(438/694).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/15 16:17
S14 7	959	(438/700).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/15 16:17
S14 8	870	(438/702).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/15 16:17
S14 9	13679	(S132 or S133 or S134 or S135 or S136 or S137 or S138 or S139 or S140 or S141 or S142 or S143 or S144 or S145 or S146 or S147 or S148)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/15 16:17
S15 0	5423	(S131 or S149) and ((micromechanical or MEMS or microelectromechanical or micromachined or microstructure$1 or (acceleration adj sensor) or accelerometer or transducer))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/15 17:03
S15 1	69980	(S150 or S127)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/15 16:18

S15 2	197	S151 and (comb$5 or electrostatic).clm. and (spring$1 or flexure$1).clm. and (distance or width).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/15 16:27
S15 3	183	S151 and (macdonald or shaw).in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/15 16:26
S15 4	72	S151 and (cornell).as.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/15 16:26
S15 5	1713	S151 and (comb$5 or electrostatic).clm. and (distance or width).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/15 16:27
S15 6	1564	S151 and comb$5 and (comb$5 or electrostatic).clm. and (distance or width).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/15 16:27
S15 7	1877	S151 and comb$5 and (comb$5 or electrostatic or $5actuator).clm. and (distance or width).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/15 16:28
S16 0	217	S151 and comb$5 and (comb$5 or electrostatic or $5actuator).clm. and (distance or width) near3 (prong$1 or teeth or tooth or finger$1 or trench$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/15 16:31
S16 1	687	S151 and comb$5 and (((second adj side) or back$1side) with (etch$3 or remov$3 or form$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/15 16:33
S16 2	412	S151 and comb$5 and (((second adj side) or back$1side) with (etch$3 or remov$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/15 16:33
S16 3	48	S151 and comb$5 and (((second adj side) or back$1side) with (etch$3 or remov$3)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/15 16:33

S16 4	210	S151 and comb$5 and (((second adj side) or back$1side) with (etch$3 or remov$3 or form$3)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/15 16:52
S16 5	2	("6753638").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/15 16:47
S16 6	429	S151 and (((second adj side) or back$1side) with (etch$3 or remov$3 or form$3)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/15 16:53
S16 7	1034	(((micromechanical or MEMS or microelectromechanical or micromachined or microstructure$1 or (acceleration adj sensor) or accelerometer or transducer)) and (((second adj side) or back$1side) with (etch$3 or remov$3 or form$3)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/15 17:03
S16 8	368	(((micromechanical or MEMS or microelectromechanical or micromachined or microstructure$1 or (acceleration adj sensor) or accelerometer or transducer)) and ((second adj side) or back$1side) with (etch$3 or remov$3 or form$3)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/15 17:04
S16 9	368	(((micromechanical or MEMS or microelectromechanical or micromachined or microstructure$1 or (acceleration adj sensor) or accelerometer or transducer)) and ((second adj side) or back$1side or backside) with (etch$3 or remov$3 or form$3)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/15 17:04
S17 0	368	(((micromechanical or MEMS or microelectromechanical or micromachined or microstructure$1 or (acceleration adj sensor) or accelerometer or transducer)) and ((second adj side) or back$1side) with (etch$3 or remov$3 or form$3)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/15 17:04

S17 1	458	(((micromechanical or MEMS or microelectromechanical or micromachined or microstructure$1 or (acceleration adj sensor) or accelerometer or transducer)) and ((second adj side) or back$1side or (bottom adj side)) with (etch$3 or remov$3 or form$3)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/15 17:04
S17 2	159	((micromechanical or MEMS or microelectromechanical or micromachined or microstructure$1 or (acceleration adj sensor) or accelerometer or transducer)) and ((shaw and kevin) or (scott and adams) or (tim and davis) or (john and chong) or (seung and lee)).in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/15 17:20
S17 3	25	((micromechanical or MEMS or microelectromechanical or micromachined or microstructure$1 or (acceleration adj sensor) or accelerometer or transducer)) and ((shaw and kevin) or (scott and adams) or (tim and davis) or (john and chong) or (seung and lee)).in. and cornell	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/15 17:20
S17 4	407	((micromechanical or MEMS or microelectromechanical or microstructure$1 or (acceleration adj sensor) or accelerometer))and (passivation).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/20 13:31
S17 5	306	((micromechanical or MEMS or microelectromechanical or microstructure$1 or (acceleration adj sensor) or accelerometer))and (passivation adj layer).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/20 13:31
S17 6	306	((micromechanical or MEMS or microelectromechanical or microstructure$1 or (acceleration adj sensor) or accelerometer)) and (passivation adj layer).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/20 13:31
S17 7	6	((micromechanical or MEMS or microelectromechanical or microstructure$1 or (acceleration adj sensor) or accelerometer)) and (passivation adj layer).clm. and (shaw or adams).in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/20 14:19

S178	282	((micromechanical or MEMS or microelectromechanical or microstructure$1 or (acceleration adj sensor) or accelerometer)) and (shaw or adams).in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/20 17:24
S179	406	((micromechanical or MEMS or microelectromechanical or microstructure$1 or (acceleration adj sensor) or accelerometer)) and (shaw or adams or macdonald).in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/20 14:20
S180	2	("5994152").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/20 15:36
S181	1326	((micromechanical or MEMS or microelectromechanical or microstructure$1 or (acceleration adj sensor) or accelerometer)) and (glass with (protect$3 or lid))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/20 17:25
S182	103	((micromechanical or MEMS or microelectromechanical or microstructure$1 or (acceleration adj sensor) or accelerometer)) and (glass with (protect$3 or lid)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/20 17:49
S183	545	((micromechanical or MEMS or microelectromechanical or microstructure$1 or (acceleration adj sensor) or accelerometer)) and (wafer with bond$3).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/21 14:03
S184	688	((micromechanical or MEMS or microelectromechanical or microstructure$1 or (acceleration adj sensor) or accelerometer)) and (thin$4 near2 (wafer or substrate)) and (SOI or silicon-on-insulator)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/20 17:51
S185	67	((micromechanical or MEMS or microelectromechanical or microstructure$1 or (acceleration adj sensor) or accelerometer)) and (thinning adj2 (wafer or substrate)) and (SOI or silicon-on-insulator)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/20 17:51